# RENESAS

# HSB83

# Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0187-0200Z (Previous: ADE-208-489A) Rev.2.00 Mar.22.2004

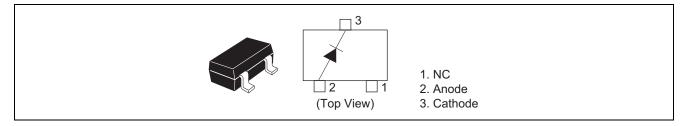
### Features

- High reverse voltage. ( $V_R = 250 \text{ V}$ )
- CMPAK package is suitable for high density surface mounting and high speed assembly.

### **Ordering Information**

Туре No.	Laser Mark	Package Code
HSB83	F7	CMPAK

### **Pin Arrangement**





## **Absolute Maximum Ratings**

			(Ta = 25°C)	
Item	Symbol	Value	Unit	
Peak reverse voltage	V <sub>RM</sub>	300	V	
Reverse voltage	V <sub>R</sub>	250	V	
Peak forward current	I <sub>FM</sub>	300	mA	
Non-Repetitive peak forward surge current	I <sub>FSM</sub> * <sup>1</sup>	2	А	
Average rectified current	lo	100	mA	
Junction temperature	Тј	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

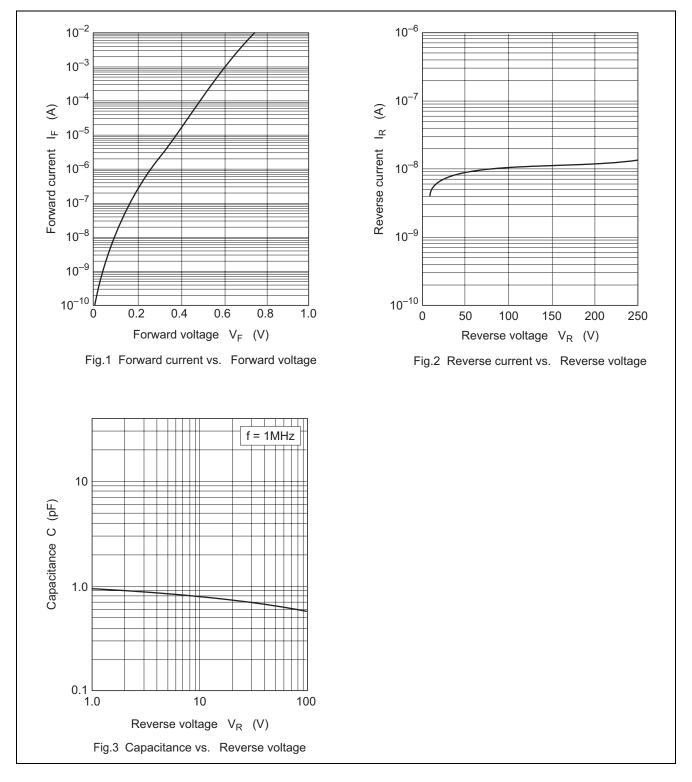
Note: 1. Value at duration of 10 ms.

## **Electrical Characteristics**

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F</sub>	_	_	1.2	V	I <sub>F</sub> = 100 mA
Reverse current	I <sub>R1</sub>	_	—	0.2	μΑ	V <sub>R</sub> = 250 V
	I <sub>R2</sub>	_	—	100		V <sub>R</sub> = 300 V
Capacitance	С	_	—	3.0	pF	$V_{R} = 0 V, f = 1 MHz$
Reverse recovery time	t <sub>rr</sub>	—	_	100	ns	$I_F = I_R = 30 \text{ mA}, I_{rr} = 3 \text{ mA}, R_L = 100 \ \Omega$

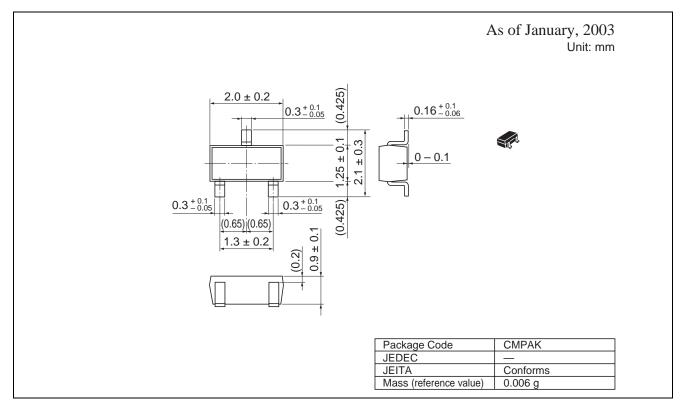


### **Main Characteristics**



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### **Package Dimensions**





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